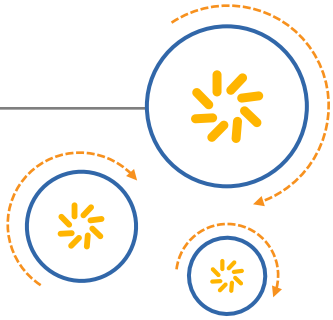
Qualcomm Technologies, Inc.



# RB02

## Hardware Release Notes

80-YA116-18 Rev. A

July 3, 2017

Qualcomm is a trademark of Qualcomm Incorporated, registered in the United States and other countries. Other product and brand names may be trademarks or registered trademarks of their respective owners.

This technical data may be subject to U.S. and international export, re-export, or transfer (“export”) laws. Diversion contrary to U.S. and international law is strictly prohibited.

Qualcomm Technologies, Inc.
5775 Morehouse Drive
San Diego, CA 92121
U.S.A.

© 2017 Qualcomm Technologies, Inc. All rights reserved.

Qualcomm Technologies, Inc. (“QTI”) and its affiliates reserve the right to make any updates, corrections and any other modifications to its documentation. The information provided in this document represents QTI’s knowledge and belief as of the date this document is provided. QTI makes no representation or warranty as to the accuracy of such information, and QTI assumes no liability for any use of the information in this documentation. You should obtain the latest information before placing orders for any hardware, and you should verify that such information is current and complete. Information published by QTI regarding any third-party products does not constitute a license to use such products or a warranty or endorsement thereof. Use of such information may require a license from a third party under the intellectual property rights of such third party, or a license from QTI or its affiliates under the intellectual property rights of QTI or its affiliates.

All hardware, equipment, components or products are sold subject to QTI’s (or such other QTI affiliated company that is designated by QTI) standard terms and conditions of sale, as applicable. Notwithstanding anything to the contrary in this documentation or otherwise: (i) you do not receive any rights, licenses, or immunities from suit under any patents of Qualcomm Incorporated, QTI or their respective affiliates as a result of receiving this documentation (whether expressly, impliedly, by virtue of estoppel or exhaustion, or otherwise), (ii) without limitation, you shall not use or sell any wireless wide area network (“WWAN”) baseband integrated circuit that you purchase or acquire from QTI or any product that incorporates any such WWAN baseband integrated circuit (whether alone or in combination with any other software or components) without a separate license or non-assertion covenant from Qualcomm Incorporated in respect of or under all applicable patents, (iii) nothing in this document modifies or abrogates your obligations under any license or other agreement between you and Qualcomm Incorporated, including without limitation any obligation to pay any royalties, and (iv) you will not contend that you have obtained any right, license, or immunity from suit with respect to any patents of Qualcomm Incorporated, QTI or their respective affiliates under or as a result of receiving this documentation (whether expressly, impliedly, by virtue of estoppel or exhaustion, or otherwise).

# Revision history

| Revision | Date | Description |
|---|---|---|
| A | July 2017 | Initial release |

# 1 Release contents

This document serves as the release notes for the RB02 Wi-Fi module. This release includes the following hardware documentation:

- QCA4010 Low-Energy Wi-Fi Single-Band 802.11b/g/n SoC Device Specification (Qualcomm Technologies' 80-YA116-1)
- RB01 Development Platform Hardware User Guide (Qualcomm Technologies' 80-YA116-13)
- RB02 Product Specification (Qualcomm Technologies' 80-YA116-12)
- RB02 Hardware Reference Guide (Qualcomm Technologies' 80-YA116-19)

# 2 Supported hardware

The RB02 module is one of the supported hardware in the Internet of Everything Wireless System Release (I-WSR) 4.1. The RB02 module uses the QCA4010 1x1 single-band 802.11b/g/n Wi-Fi SoC and supports 2.4 GHz operation.

The RB02 module can be either used with the RB01 for software development or incorporated into OEM products to enable rapid deployment of Wi-Fi connected systems.

# 3 RB02 change history

**Table 1 RB02 module revisions**

| Revision | Module no. | Change |
|---|---|---|
| CUS511-010 | 20-YA025-H1 | – |
| RB02-010 | 20-YA163-H1 | ▪ DNI R306<br>▪ Deleted the I2CM_SDA1 connection (U1.A3 pin to H43 Pad)<br>▪ Deleted the I2CM_SCL1 connection (U1.B32 pin to H44 Pad)<br>▪ Added the I2CM_SDA0 connection (U1.A58 pin to H43 Pad)<br>▪ Added the I2CM_SCK0 connection (U1.B47 pin to H44 Pad) |